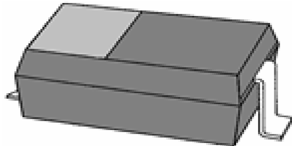
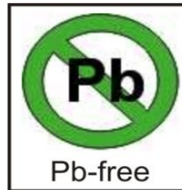
SEMICONDUCTOR
Small Signal Products

MATERIAL CONTENT LIST

PACKAGE FAMILY: **SOD-123**
DATE: **21-Apr-2009**
REVISION: **13**





MATERIAL CONTENT					
Part	**Material**	**CAS N°**	**weight mg**	**% of weight**	**ppm of total weight**
Mold compound 73.8% (raw material before curing)	Silcon Fused	60676-86-0	5.62	74.0%	545843
	Epoxy Resin	29690-82-2	0.76	10.0%	73763
	Phenol Novalac	9003-35-4	0.76	10.0%	73763
	Mixed Siloxanes	2530-83-8	0.23	3.0%	22129
	Antimony Trioxide	1309-64-4	0.08	1.0%	7376
	Brominated Compound	40039-93-8	0.08	1.0%	7376
	Carbon	7440-44-0	0.08	1.0%	7376
	TOTAL		**7.60**		
Lead frame 23.9%	Si	7440-21-3	0.008	0.3%	776
	Mn	7439-96-5	0.020	0.8%	1941
	Ni	7440-02-0	0.95	38.5%	92203
	Co	7440-48-4	0.01	0.4%	971
	Fe	7439-89-6	1.4	56.8%	135879
	Cr	7440-47-3	0.0025	0.1%	243
	C	7440-44-0	0.0005	0.02%	49
	Cu	7440-50-8	0.003	0.1%	243
	Ag	7440-22-4	0.072	2.9%	6988
	TOTAL		**2.47**		
Terminal finish 1.4%	Sn	7440-31-5	0.142	100.0%	13782
	TOTAL		**0.14**		
Silicon chip 0.8%	Si	7440-21-3	0.074	91.6%	7182
	SiO2	14808-60-7	0.0003	0.4%	31
	Au	7440-57-5	0.0065	8.0%	631
	And / or traces of As, Ag, Ti, Al, Ni, Pd, Cu				
	TOTAL		**0.08**		
Bond wire 0.1%	Au	7440-57-5	0.015	100.0%	1456
	TOTAL		**0.015**		
Total weight			**10.3**		

Remark: Total weight range ± 10%
Reflow Soldering acc. J-STD-020D
Material Analyses Reports available on request